

SPI 2020

24th IEEE Workshop On Signal And Power Integrity

May 17-20 2020, Cologne, Germany

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Important Dates

Full Paper Submission: January 31st, 2020

Notification of Acceptance: March 2nd, 2020

Call for Papers

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Over the past two decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

The Committee is looking forward to the 24th Edition which will convene Cologne, the very heart of the Rhineland. The SPI 2020 technical program will include both oral and poster sessions. A number of prominent experts will be giving tutorials on areas of emerging interest. The Conference Proceedings will be published with an ISBN code and will appear in IEEE Xplore.

Topics

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- AI in electronics design

